

J1017 U.S. PTO
10/09/02
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PATENT NUMBER and
ISSUE DATE

U.S. UTILITY Patent Application

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10043709	01/09/2002	25	678	281	5-10-02

**APPLICANTS: Chou Kuo-Yu; Lee Tze-Liang; Ong Tong-Chern;

**CONTINUING DATA VERIFIED: No

** FOREIGN APPLICATIONS VERIFIED: No

PG-PUB DO NOT PUBLISH ☐

RESCIND ☐

Foreign priority claimed

☐ yes ☒ no

35 USC 119 conditions met

☐ yes ☒ no

Verified and Acknowledged Examiners's initials

TL

ATTORNEY DOCKET NO

67,200-603

TITLE : Single layer wiring bond pad with optimum AL film thickness in Cu/FSG process for devices under pads

U.S. DEPT. OF COMM./PAT. & TR. PTO-435L (Rev. 12-94)

NOTICE OF ALLOWANCE MAILED

CLAIMS ALLOWED

Assistant Examiner

Total Claims

Print Claim for
O.G.

ISSUE FEE

Amount Due

Date Paid

DRAWING

Sheet to Draw

Fig. to Draw

Print Fig.

Primary Examiner

PREPARED FOR ISSUE

Application Examiner

☐ TERMINAL

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☐ CD-ROM

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